


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	IPG/15/9036	
1.3 Title of PCN	Micro Leadframe Package conversion to High Density for E-Fuse product Family	
1.4 Product Category	Linear Voltage Regulator	
1.5 Issue date	2015-01-21	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Antonio RIVIERA
2.1.3 Quality Manager	Paolo MORETTI

**3. Change**

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, ...)	CARSEM

**4. Description of change**

	Old	New
4.1 Description	STD FRAME, Au wire bonding, Molding compound G770HC, Glue for controller die 8006NS	Micro Lead-frame Package (MLP) built on standard Lead-frame will be converted to High Density Lead-frame (HDL) on E-Fuse product family assembled in FPN 3x3mm2 package in Carsem (Suzhou). We grabbed the opportunity to improve the bill of Material too by using a new Glue (HITACHI 4900GCN3) for the Controller Die, the Cu Wire Bonding and an upgraded dedicated molding compound (G770HCD) packaged in a MSL3. The combination of HDL and G770HCD has been already qualified and it is running in production on similar product/packages
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

**5. Reason / motivation for change**

5.1 Motivation	The HDL implementation will bring to a higher production capability and to a better frame handling that it is translated in a better product quality. On the other hand these changes will harmonize the Bill of Material in CARSEM site.
5.2 Customer Benefit	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

6.1 Description	see traceability code
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**7. Timing / schedule**

7.1 Date of qualification results	2014-12-18
7.2 Intended start of delivery	2015-03-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	250-W-14-UW70-STEF05WPUR in VDFPN 3x3-10L (New BOM)-PCN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2015-01-21

9. Attachments (additional documentations)	
9036PpPrdtLst.pdf 250-W-14-UW70-STEF05WPUR in VDFPN 3x3-10L (New BOM)-PCN.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STEF05DPUR	

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